## General Description

The AAT1236 is a highly integrated, high efficiency power solution for white LED and keypad backlights in mobile/portable devices. It is based on a switching boost converter which steps up the single cell lithi-um-ion/polymer battery voltage to drive 5 strings of series-connected white LEDs with precision current regulation. The AAT1236 is capable of driving a total of four LEDs per channel.

The boost converter can produce an output drive of up to 24 V at 100 mA . The high switching frequency (up to 2 MHz ) provides fast response to load transients and allows the use of small external components. A fully integrated control circuit simplifies the design and reduces total solution size.

A two-wire $I^{2} \mathrm{C}$ serial digital interface is used to individually turn each output sink on/off and adjust the LED current by group. Unlike conventional pulse width modulation (PWM) control of LED brightness, the AAT1236 drives the LEDs with constant, nonpulsating current. The interface is fully compliant to the Fast/Standard mode $I^{2} \mathrm{C}$ specification, allowing a transfer rate of up to 400 kHz .

A similar device is also available with a proprietary Advanced Simple Serial Control ${ }^{T M}$ ( AS $^{2}$ Cwire ${ }^{T M}$ ) single wire interface; please see the AAT1235 datasheet.

The AAT1236 is available in a Pb-free, thermallyenhanced 16 -pin $3 x 4 \mathrm{~mm}$ TDFN package and is specified for operation over the $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ temperature range.

## Features

## SwitchReg ${ }^{\text {m }}$

- Input Supply Voltage Range: 2.7 V to 5.5 V
- Maximum Boost Output Drive: Up to 24 V at 100 mA
- Up to 85\% Efficient Operation
- Up to 2 MHz Switching Frequency with Small Inductor
- User-Programmable Full-Scale LED Current, Up to 30 mA
- Two-Wire, $I^{2} \mathrm{C}$ Compliant Serial Interface - Two Addressable Registers
- Independent LED Current Control by Group
- Backlight Group B1-B2, 16 Settings
- Auxiliary Group A1-A3, 16 Settings
- Independent LED ON/OFF Control
- Fast, 400kHz Serial Transfer Rate
- Non-Pulsating, High-Performance LED Current Drive for Uniform Illumination
- 10\% Absolute Accuracy
- 2\% Channel-to-Channel Matching
- Over-Voltage and Over-Temperature Protection
- Automatic Soft-Start Minimizes Large Inrush Current at Startup
- Available in 3x4mm TDFN34-16 Package


## Applications

- Digital Still Cameras (DSCs)
- Keypad Backlight
- Large Panel Displays
- Mobile Handsets
- PDAs and Notebook PCs
- Personal Media Players
- White LED Backlight


## Typical Application



## Pin Descriptions

| Pin \# | Symbol | Function |
| :---: | :---: | :--- |
| 1 | VIN | Input supply for the converter. Connect a 2.2 $\mu$ F or larger ceramic capacitor from VIN to GND. |
| 2 | OV | Boost output over voltage detect pin. Use resistor divider to set the circuit's external over- <br> voltage protection. See Applications Information for details. |
| 3 | EN | Enable pin. |
| 4 | B1 | Backlight current sink 1. Connect the cathode of the last LED in the string to B1. |
| 5 | B2 | Backlight current sink 2. Connect the cathode of the last LED in the string to B2. |
| 6 | RSET | LED current set resistor. A 22.6k $\Omega$ resistor from RSET to AGND sets the maximum LED cur- <br> rent in A1-A3 and B1-B2 to 20mA. |
| 7 | IN | Input bias supply for the internal circuitry. Connect IN to VIN directly at the AAT1236. |
| 8 | GND | Power ground for the boost converter. Connect GND to AGND at a single point as close to <br> the AAT1236 as practical. |
| 9 | SW | Boost converter switching node. A 2.2 $\mu$ H inductor, connected between SW and LIN, sets the <br> boost converter's switching frequency. |
| 10 | SDA | I'C interface serial data line. |
| 11 | SCL | I²C interface serial clock line. |
| 12 | AGND | Ground pin. Connect AGND to GND at a single point as close to the AAT1236 as practical. |
| 13 | A3 | Auxiliary current sink 3. Connect the cathode of the last LED in the string to A3. |
| 14 | A2 | Auxiliary current sink 2. Connect the cathode of the last LED in the string to A2. |
| 15 | A1 | Auxiliary current sink 1. Connect the cathode of the last LED in the string to A1. |
| 16 | LIN | Switched power input. Connect LIN to the external power inductor. |
| EP |  | Exposed paddle (bottom). Connected internally to SW. Connect to SW or leave floating. |

## Pin Configuration

TDFN34-16
(Top View)


## Absolute Maximum Ratings ${ }^{1}$

$\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted.

| Symbol | Description | Value | Units |
| :---: | :--- | :---: | :---: |
| VIN, IN | Input Voltage | -0.3 to 6.0 | V |
| SW | Switching Node | 28 | V |
| EN, SCL, SDA, Bx, <br> $\mathrm{Ax}, \mathrm{RSET}, \mathrm{OV}, \mathrm{LIN}$ | Maximum Rating | $\mathrm{V}_{\text {IN }}+0.3$ | V |
| $\mathrm{~T}_{\mathrm{S}}$ | Storage Temperature Range | -65 to 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{J}}$ | Operating Temperature Range | -40 to 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {LEAD }}$ | Maximum Soldering Temperature (at leads, 10 sec) | 300 | ${ }^{\circ} \mathrm{C}$ |

## Thermal Information ${ }^{2}$

| Symbol | Description | Value | Units |
| :---: | :--- | :---: | :---: |
| $\theta_{\mathrm{JA}}$ | Thermal Resistance | 50 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{P}_{\mathrm{D}}$ | Maximum Power Dissipation ${ }^{3}$ | 2 | W |

[^0]
## Electrical Characteristics ${ }^{1}$

$\mathrm{V}_{\mathrm{IN}}=3.6 \mathrm{~V} ; \mathrm{C}_{\mathrm{IN}}=2.2 \mu \mathrm{~F} ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.

| Symbol | Description | Conditions | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Power Supply |  |  |  |  |  |  |
| $\mathrm{V}_{\text {IN }}$ | Input Voltage Range |  | 2.7 |  | 5.5 | V |
| $\mathrm{V}_{\text {OUT(MAX) }}$ | Maximum Output Voltage |  |  |  | 24 | V |
| $\mathrm{V}_{\text {UVLO }}$ | UVLO Threshold | $\mathrm{V}_{\text {IN }}$ Rising |  |  | 2.7 | V |
|  |  | Hysteresis |  | 150 |  | mV |
|  |  | $\mathrm{V}_{\text {IN }}$ Falling | 1.8 |  |  | V |
| $I_{\text {cc }}$ | Operating Current (No Switching) | $\begin{aligned} & \mathrm{B} 1=\mathrm{B} 2=\mathrm{A} 1=\mathrm{A} 2=\mathrm{A} 3=1.2 \mathrm{~V}, \\ & 2 \mathrm{~mA} \text { Setting, } \mathrm{R}_{\mathrm{SET}}=226 \mathrm{k} \Omega \end{aligned}$ |  |  | 300 | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\text {SHDN(MAX })}$ | VIN Pin Shutdown Current | EN = GND |  |  | 1.0 | $\mu \mathrm{A}$ |
| $\mathrm{I}_{0 \mathrm{X}}$ | Maximum Continuous Output Current | $\mathrm{V}_{\mathrm{O}}=24 \mathrm{~V}$ | 100 |  |  | mA |
| $\mathrm{I}_{\mathrm{DX}}$ | Current Sink Accuracy | $\mathrm{R}_{\text {SET }}=22.6 \mathrm{k} \Omega$ | 18 | 20 | 22 | mA |
| IDX-Matching | Current Matching Between Any Sink Channels | $\begin{aligned} & \mathrm{R}_{\mathrm{SET}}=22.6 \mathrm{k} \Omega, \\ & \mathrm{~A} 1=\mathrm{A} 2=\mathrm{A} 3=\mathrm{B} 1=\mathrm{B} 2=0.4 \mathrm{~V} \end{aligned}$ |  | 2 | 5 | \% |
| $\mathrm{V}_{\text {OV }}$ | OVP Threshold Voltage | $\mathrm{V}_{\text {OUT }}$ Rising | 1.1 | 1.2 | 1.3 | V |
|  | OVP Threshold Hysteresis |  |  | 100 |  | mV |
| $\mathrm{R}_{\text {DS(ON)N }}$ | Low Side Switch On Resistance | $\mathrm{I}_{\text {OUT }}=100 \mathrm{~mA}$ |  | 80 |  | $\mathrm{m} \Omega$ |
| $\mathrm{R}_{\mathrm{DS}(\mathrm{ON}) \mathrm{IN}}$ | Input Disconnect Switch | $\mathrm{I}_{\text {OUT }}=100 \mathrm{~mA}$ |  | 200 |  | $\mathrm{m} \Omega$ |
| $\mathrm{T}_{\mathrm{SS}}$ | Soft-Start Time | From Enable to Output Regulation; $\mathrm{V}_{\mathrm{FB}}=300 \mathrm{mV}$ |  | 300 |  | $\mu \mathrm{s}$ |
| $\mathrm{I}_{\text {SET }}$ | Current Set Ratio | $\mathrm{I}_{\text {SINK }} / \mathrm{I}_{\text {RSET }}, \mathrm{V}_{\text {RSET }}=0.6 \mathrm{~V}$ |  | 760 |  | A/A |
| $\mathrm{I}_{\text {LIMIT }}$ | Input Switch Current Limit |  | 1.2 |  |  | A |
| Enable Input - EN |  |  |  |  |  |  |
| $\mathrm{V}_{\text {EN(L) }}$ | Enable Threshold Low |  |  |  | 0.4 | V |
| $\mathrm{V}_{\text {EN(H) }}$ | Enable Threshold High |  | 1.4 |  |  | V |
| $I^{2} \mathrm{C}$ Serial Interface - SCL, SDA |  |  |  |  |  |  |
| $\mathrm{F}_{\text {SCL }}$ | Clock Frequency |  |  |  | 400 | kHz |
| T Low | Clock Low Period |  | 1.3 |  |  | $\mu \mathrm{s}$ |
| $\mathrm{T}_{\text {HIGH }}$ | Clock High Period |  | 0.6 |  |  | $\mu \mathrm{s}$ |
| $\mathrm{T}_{\text {HD_STA }}$ | Hold Time START Condition |  | 0.6 |  |  | $\mu \mathrm{s}$ |
| $\mathrm{T}_{\text {SU_STA }}$ | Setup Time for Repeat START |  | 0.6 |  |  | $\mu \mathrm{s}$ |
| $\mathrm{T}_{\text {SU_DAT }}$ | Data Setup Time |  | 100 |  |  | ns |
| $\mathrm{T}_{\text {HD_DAT }}$ | Data Hold Low |  | 0 |  | 0.9 | $\mu \mathrm{s}$ |
| $\mathrm{T}_{\text {SU_STO }}$ | Setup Time for STOP Condition |  | 0.6 |  |  | $\mu \mathrm{s}$ |
| $\mathrm{T}_{\text {BUF }}$ | Bus Free Time Between STOP and START Condition |  | 1.3 |  |  | $\mu \mathrm{s}$ |
| $\mathrm{V}_{\text {IL }}$ | Input Threshold Low | $2.7 \leq \mathrm{V}_{\mathrm{IN}} \leq 5.5$ |  |  | 0.4 | V |
| $\mathrm{V}_{\mathrm{IH}}$ | Input Threshold High | $2.7 \leq \mathrm{V}_{\mathrm{IN}} \leq 5.5$ | 1.4 |  |  | V |
| $I_{1}$ | Input Current |  | -1.0 |  | 1.0 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\mathrm{OL}}$ | Output Logic Low (SDA) | $\mathrm{I}_{\text {PULLUP }}=3 \mathrm{~mA}$ |  |  | 0.4 | V |

1. The AAT1236 is guaranteed to meet performance specifications over the $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ operating temperature range and is assured by design, characterization, and correlation with statistical process controls.

## Electrical Characteristics (continued) ${ }^{1}$

$\mathrm{V}_{\mathrm{IN}}=3.6 \mathrm{~V} ; \mathrm{C}_{\mathrm{IN}}=2.2 \mu \mathrm{~F} ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.

| Symbol | Description | Conditions | Min | Typ | Max | Units |
| :---: | :--- | :--- | :--- | :--- | :---: | :---: |
| Thermal Protection |  |  | 140 |  | ${ }^{\circ} \mathrm{C}$ |  |
| $\mathrm{T}_{\text {J-TH }}$ | $\mathrm{T}_{\mathrm{J}}$ Thermal Shutdown Threshold |  |  | 15 |  | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {J-HYS }}$ | $\mathrm{T}_{J}$ Thermal Shutdown Hysteresis |  |  |  |  |  |

## I ${ }^{2} \mathrm{C}$ Interface Timing Details



1. The AAT1236 is guaranteed to meet performance specifications over the $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ operating temperature range and is assured by design, characterization, and correlation with statistical process controls.

## Typical Characteristics

Efficiency vs. LED Current (Group B On; Group A Off)


Efficiency vs. LED Current (Group A and B On)


## LED Current vs. Supply Voltage



Efficiency vs. LED Current (Group B Off; Group A On)


LED Current Accuracy vs. Supply Voltage


Shutdown Current vs. Supply Voltage and Temperature


## Typical Characteristics



Shutdown Operation
(All Channels)


Time ( $50 \mu \mathrm{~s} / \mathrm{div}$ )


LED Current Accuracy vs. Temperature (All Channels $=\mathbf{2 0 m A}$ )


Output Ripple
(All Channels $=20 \mathrm{~mA}$ )


Switching Frequency vs. Supply Voltage and Temperature


# ANALOGIC TECH 

AAT1236<br>High Efficiency White LED Drivers for Backlight and Keypad

## Typical Characteristics



Time (50 $\mu \mathrm{s} / \mathrm{div}$ )

Enable Threshold High vs.
Supply Voltage and Temperature


Low Side Switch On Resistance vs. Supply Voltage and Temperature


Enable Threshold Low vs. Supply Voltage and Temperature


Input Disconnect Switch Resistance vs. Supply Voltage and Temperature


Soft Start Operation
(All Channels $=20 \mathrm{~mA}$ )


Time ( $200 \mu \mathrm{~s} / \mathrm{div}$ )

## Typical Characteristics

Transition of LED Current
(All Channels $=20 \mathrm{~mA}$ to 1.8 mA )


Time ( $100 \mu \mathrm{~s} / \mathrm{div}$ )


Time ( $100 \mu \mathrm{~s} / \mathrm{div}$ )

## Functional Block Diagram



## Functional Description

The AAT1236 consists of a controller for the step-up switching converter and its power switch, and five regulated current sinks programmable over 16 levels into two groups, which can be turned on/off individually. An external Schottky diode, a power inductor, an output capacitor, and a resistor divider are required to complete the solution.
The AAT1236's boost controller is designed to deliver 100 mA up to 24 V . The AAT1236 is capable of driving a total of five channels divided into two groups with four white LEDs connected in series at each channel.

The output load current can be programmed by the current sink magnitudes. $I^{2} C$ interface programming allows independent control of two groups of
current sinks (A1 to A3 and B1 to B2) and control on/off with a different configuration on each channel. Unused sink channel(s) must be connected to AGND to ensure proper function of the AAT1236.

## Control Loop

The AAT1236 provides the benefits of current mode control with a simple hysteretic output current loop providing exceptional stability and fast response with minimal design effort. The device maintains exceptional constant current regulation, transient response, and cycle-by-cycle current limit without additional compensation components.

The AAT1236 modulates the power MOSFET switching current to maintain the programmed sink current through each channel. The sink voltage at each channel is monitored and the controller pro-
vides direct feedback in order to maintain the desired LED currents.

The switching cycle initiates when the N -channel MOSFET is turned ON and current ramps up in the inductor. The ON interval is terminated when the inductor current reaches the programmed peak current level. During the OFF interval, the input current decays until the lower threshold, or zero inductor current, is reached. The lower current is equal to the peak current minus a preset hysteresis threshold, which determines the inductor ripple current. Peak current is adjusted by the controller until the desired LED output current level is met.

The magnitude of the feedback error signal determines the average input current. Therefore, the AAT1236 controller implements a programmed current source connected to the output capacitor, parallel with the LED channels. There is no right-half plane zero, and loop stability is achieved with no additional compensation components. The controller responds by increasing the peak inductor current, resulting in higher average current in the inductor and LED channels.

Under light load conditions, the inductor OFF interval current goes below zero and the boost converter enters discontinuous mode operation. Further reduction in the load current results in a corresponding reduction in the switching frequency. The AAT1236 provides pulsed frequency operation which reduces switching losses and maintains high efficiency under light load conditions.

Operating frequency varies with changes in the input voltage, output voltage, and inductor size. Once the boost converter has reached continuous mode, further increases in the LED current will not significantly change the operating frequency. A small $2.2 \mu \mathrm{H}( \pm 20 \%)$ inductor is selected to maintain high frequency switching (up to 2 MHz ) and high efficiency operation for outputs up to 24 V .

## Soft Start / Enable

The input disconnect switch is activated when a valid supply voltage is present and the EN/SET pin is strobed high. Slew rate control on the input disconnect switch ensures minimal inrush current as
the output voltage is charged to the input voltage, prior to switching of the N -channel power MOSFET. A monotonic turn-on is guaranteed by the built-in soft-start circuitry, which eliminates output current overshoot across the full input voltage range and over all load conditions.

## Current Limit and Over-Temperature Protection

The switching of the N-channel MOSFET terminates when a current limit of 1.5 A (typical) is exceeded. This minimizes power dissipation and component stresses under overload and short-circuit conditions. Switching resumes when the current decays below the current limit.

Thermal protection disables the AAT1236 when internal power dissipation becomes excessive, as it disables both MOSFETs. The junction over-temperature threshold is $140^{\circ} \mathrm{C}$ with $15^{\circ} \mathrm{C}$ of temperature hysteresis. The output voltage automatically recovers when the over-temperature fault condition is removed.

## Over-Voltage Protection

Over-voltage protection prevents damage to the AAT1236 during open-circuit on any LED channel causing high output voltage conditions. An overvoltage event is defined as a condition where the voltage on the OV pin exceeds the over-voltage threshold limit ( $\mathrm{V}_{\mathrm{OV}}=1.2 \mathrm{~V}$ typical). When the voltage on the OV pin has reached the threshold limit, the converter stops switching and the output voltage decays. Switching resumes when the voltage on the OV pin drops below the lower hysteresis limit, maintaining an average output voltage between the upper and lower OV thresholds multiplied by the resistor divider scaling factor.

## Under-Voltage Lockout

Internal bias of all circuits is controlled via the $\mathrm{V}_{\mathrm{IN}}$ input. Under-voltage lockout (UVLO) guarantees sufficient $\mathrm{V}_{\mathrm{IN}}$ bias and proper operation of all internal circuitry prior to soft start.

## $I^{2} C$ Serial Interface and Programmability

The current sink magnitude of each group and the on/off status of each channel is controlled via an $I^{2} \mathrm{C}$ serial interface. $I^{2} \mathrm{C}$ is a widely used interface which requires a master to initiate all the communications with the device. $I^{2} \mathrm{C}$ protocol consists of two active wire SDA (serial data line) and SCL (serial clock line). Both wires are open drain and require an external pull-up resistor to $\mathrm{V}_{\mathrm{cc}}$. The SDA pin serves the I/O function, and the SCL pin controls and references the $I^{2} \mathrm{C}$ bus. The $I^{2} \mathrm{C}$ protocol is a bidirectional bus which allows both read and write actions to take place; the AAT1236 supports the write protocol only. Since the protocol has a dedicated bit for Read or Write ( $R / \bar{W}$ ), when communicating with the AAT1236, this bit must be set to " 0. "

## $I^{2} \mathrm{C}$ Programming Register Address and Register Data

After sending the device address, the $I^{2} C$ master should send an 8 -bit register address and 8 -bit data for programming. The AAT1236 has two registers; The Brightness Control Register determines the percentage of the maximum current set by $\mathrm{R}_{\mathrm{SET}}$ applied to each channel and the Channel Control Register determines which channels are enabled or disabled. The programming is as follows:
BR_CRTL-LEDBrightness Control Register (Address: 00h)

| BR_CTRL | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Bit name | BX3 | BX2 | BX1 | BX0 | AX3 | AX2 | AX1 | AX0 |

Control register BR_CRTL can be used to control LED brightness for each group. Control bits BX3, $B X 2, B X 1, B X 0$ set the percentage of the maximum LED level in Group B. Control bits AX3, AX2, AX1, AXO set the percentage of the maximum LED level in Group A.

| BR_CTRL <br> [BX3:BX0], [AX3:AX0] | All Outputs (\%) |
| :---: | :---: |
| 0000 | 100 |
| 0001 | 84 |
| 0010 | 71 |
| 0011 | 60 |
| 0100 | 51 |
| 0101 | 43 |
| 0110 | 35 |
| 0111 | 31 |
| 1000 | 26 |
| 1001 | 21 |
| 1010 | 18 |
| 1011 | 15 |
| 1100 | 13.5 |
| 1101 | 12.0 |
| 1110 | 10.5 |
| 1111 | 9.0 |

Table 1: LED Current Setting as Percentage of the Maximum Level Set by $\mathrm{R}_{\mathrm{SET}}$.

CH_CRTL-Channel ON/OFF Control Register (Address: 01h)

| CH_CTRL | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Bit name | - | - | - | BY1 | BY2 | AY1 | AY2 | AY3 |

Control register CH_CRTL can be used to disable (OFF) or enable (ON) individual channels.

| CH_CTRL [BY1:BY2] | B1 | B2 |
| :---: | :---: | :---: |
| 00 | OFF | OFF |
| 01 | OFF | ON |
| 10 | ON | OFF |
| 11 | ON | ON |


| CH_CTRL <br> [AY1:AY3] | A1 | A2 | A3 |
| :---: | :---: | :---: | :---: |
| 000 | OFF | OFF | OFF |
| 001 | OFF | OFF | ON |
| 010 | OFF | ON | OFF |
| 011 | OFF | ON | ON |
| 100 | ON | OFF | OFF |
| 101 | ON | OFF | ON |
| 110 | ON | ON | OFF |
| 111 | ON | ON | ON |

AAT1236<br>High Efficiency White LED Drivers for Backlight and Keypad

## Application Information

## ${ }^{2}{ }^{2} \mathrm{C}$ Serial Interface

The AAT1236 is fully compliant with the industrystandard $I^{2} \mathrm{C}$ interface. The $\mathrm{I}^{2} \mathrm{C}$ two-wire communications bus consists of SDA and SCL lines. SDA provides data, while SCL provides clock synchronization. SDA data transfers device address followed by a register address and data bits sequence. When using the $I^{2} C$ interface, EN/SET is pulled high to enable the device or low to disable the device. The $I^{2} \mathrm{C}$ serial interface requires a master to initiate all the communications with target devices. The AAT1236 is a target device and only supports the write protocol. The AAT1236 is manufactured with a target device address of $0 x 36$ (Hex). See Figure 1 for the $I^{2} \mathrm{C}$ interface diagram.

## $I^{2} \mathrm{C}$ START and STOP Conditions

START and STOP conditions are always generated by the master. Prior to initiating a START, both the SDA and SCL pins are in idle mode (idle mode is when there is no activity on the bus and both SDA and SCL are pulled high by the external pullup resistors). A START condition occurs when the master pulls the SDA line low and, after a short period, pulls the SCL line low. A START condition acts as a signal to all ICs that transmission activity is about to occur on the BUS. A STOP condition, as shown in Figure 2, is when the master releases the bus and SCL changes from low to high followed by SDA low-to-high transition.

## ${ }^{12} \mathrm{C}$ Address Bit Map

Figure 3 illustrates the address bit transfer. The 7bit address is transferred with the Most Significant Bit (MSB) first and is valid when SCL is high. This is followed by the R/W bit in the Least Significant Bit (LSB) location. The R/W bit determines the direction of the transfer ('1' for read, '0' for write). The AAT1236 is a write-only device and this bit must be set low. The Acknowledge bit (ACK) is set to low by the AAT1236 to acknowledge receipt of the address.

## $I^{2}$ C Register Address / Data Bit Map

Figure 4 illustrates the Register Address or the data bit transfer. The 8-bit data is always transferred with the most significant bit first and is valid when SCL is high. The Acknowledge bit (ACK) is set low by the AAT1236 to acknowledge receipt of the register address or the data.

## $1^{2} \mathrm{C}$ Acknowledge Bit (ACK)

The Acknowledge bit is the ninth bit of each transfer on the SDA line. It is used to send back a confirmation to the master that the data has been received properly by the target device. For each ACK to take place, the master must first release the SDA line, then the target device will pull the SDA line low, as shown in Figures 1, 3 and 4.


Figure 1: $I^{2} \mathrm{C}$ Serial Interface Diagram.


STOP


Figure 2: $I^{2} \mathrm{C}$ Start and Stop Conditions;
START: A High "1" to Low "0" Transition on the SDA Line While SCL is High "1" STOP: A Low "0" to High "1" Transition on the SDA Line While SCL is High "1."


Figure 3: $I^{2} \mathrm{C}$ Device Address Bit;
7-bit Slave Address (A6-A0), 1-bit Read/Write (R/W), 1-bit Acknowledge (ACK).


Figure 4: ${ }^{2}{ }^{2} \mathrm{C}$ Register Address and Data Bit Map; 8-bit Data (D7-D0), 1-bit Acknowledge (ACK).

## $I^{2}$ C Software Protocol Example

The AAT1236 I ${ }^{2} \mathrm{C}$ programming protocol is shown in the following two examples, detailing the device address, register address and data bits. Figure 5 shows the $I^{2} \mathrm{C}$ transfer protocol.

## Example 1:

Turn on Group A with $15 \%$ from the max current setting and turn on Group B with $51 \%$ from the max current setting.

1. Send a start condition
2. Send the AAT1236's I ${ }^{2} \mathrm{C}$ device address ( $0 \times 36$ ) with the R/W bit set low
3. Wait for the acknowledge (ACK) bit within the clock cycle
4. Send the BR_CTRL register address ( $0 \times 00$ )
5. Wait for the ACK bit within the clock cycle
6. Send the BR_CTRL Data ( $0 \times 4 \mathrm{~B}$ )
7. Wait for the ACK bit within the clock cycle
8. Send the CH_CTRL register address ( $0 \times 01$ )
9. Wait for the ACK bit within the clock cycle
10. Send the CH_CTRL Data ( $0 \times 1$ F)
11. Wait for the ACK bit within the clock cycle
12. Send the stop condition

## Example 2:

Turn on A1 and A3 with $43 \%$ for the max LED current setting and turn on Group B with $100 \%$ for the max LED current setting. Figure 6 shows the $I^{2} \mathrm{C}$ transfer protocol.

1. Send a start condition
2. Send the AAT1236's $I^{2} C$ device address ( $0 \times 36$ ) with the $R / \bar{W}$ bit set low
3. Wait for the acknowledge (ACK) bit within the clock cycle
4. Send the BR_CTRL register address ( $0 \times 00$ )
5. Wait for the ACK bit within the clock cycle
6. Send the BR_CTRL Data ( $0 \times 05$ )
7. Wait for the ACK bit within the clock cycle
8. Send the CH_CTRL register address ( $0 \times 01$ )
9. Wait for the ACK bit within the clock cycle
10. Send the CH_CTRL Data (0x1D)
11. Wait for the ACK bit within the clock cycle
12. Send the stop condition

## Channel Disable

Tie all unused channels to AGND. On start-up these channels will be automatically disabled.

## LED Selection

Although the AAT1236 is specifically designed to drive white LEDs, the device can also be used to drive most types of LEDs with forward voltages ranging between 2.0 V and 4.7 V . Since the A1, A2, $A 3$, and $B 1, B 2$ input current sinks are matched with low voltage dependence, the LED-to-LED brightness will be matched regardless of the individual LED forward voltage ( $\mathrm{V}_{\mathrm{F}}$ ) levels. In some instances, it may be necessary to drive high- $\mathrm{V}_{\mathrm{F}}$ type LEDs. The low dropout ( $\sim 0.1 \mathrm{~V} @ 20 \mathrm{~mA} \mathrm{I}_{\text {LED }}$ ) current sinks in the AAT1236 make it capable of driving LEDs with forward voltages as high as 4.7 V from an input supply as low as 3.0V. LED outputs A1-A3 and B1-B2 can be combined to drive high-current LEDs without complication, making the AAT1236 a perfect application for large LCD display backlighting and keypad LED applications.


Figure 5: ${ }^{2} \mathrm{C}$ Transfer Protocol for Example 1.


Figure 6: $1^{2} \mathrm{C}$ Transfer Protocol for Example 2.

## Constant Current Setting

The LED current is controlled by the $\mathrm{R}_{\text {SET }}$ resistor. For maximum accuracy, a $1 \%$ tolerance resistor is recommended. Table 2 shows the $\mathrm{R}_{\text {SET }}$ resistor value for AAT1236 for various LED full-scale current levels.

| $\left.\mathbf{I}_{\text {LED }} \mathbf{( m A}\right)$ | $\left.\mathbf{R}_{\mathbf{S E T}} \mathbf{( k \Omega} \mathbf{\Omega}\right)$ |
| :---: | :---: |
| 30 | 14.7 |
| 25 | 17.4 |
| 20 | 22.6 |
| 15 | 29.4 |
| 10 | 44.2 |
| 5 | 93.1 |

Table 2: Maximum LED Current and $\mathrm{R}_{\text {SET }}$ Resistor Values (1\% Resistor Tolerance).

Maximum LED current per channel versus $\mathrm{R}_{\text {SET }}$ value is shown in Figure 7.


Figure 7: LED Current vs. $\mathrm{R}_{\text {SET }}$ Values.


1: $2.2 \mu \mathrm{H}$ Taiyo Yuden NR4018T2R2M
C1: 0805 10V 2.2 $\mu \mathrm{F}$ X7R GRM21BR71A225KA01
C2: 0805 25V 2.2uF X7R GRM21BR71E225KA73L
LED1-24: OSRAM LW M673 or equivalent
Figure 8: A AAT1236-based High Efficiency White LED Driver Schematic.

## Over-Voltage Protection

The over-voltage protection circuit consists of a resistor network connected from the output voltage to the OV pin (see Figure 9). This over voltage protection circuit prevents damage to the device when one of the five channels has an open LED circuit. The AAT1236 continues to operate; however, the LED current in the remaining channels is no longer regulated and the actual LED current will be determined by the externally programmed over-voltage protection threshold, the inductor value, and the switching frequency.

The resistor divider can be selected such that the over-voltage threshold occurs prior to the output reaching $24 \mathrm{~V}\left(\mathrm{~V}_{\text {OUt(MAX) }}\right)$. The value of R 3 should be selected from $10 \mathrm{k} \Omega$ to $20 \mathrm{k} \Omega$ to minimize switching losses without degrading noise immunity.

$$
\mathrm{R}_{2}=\mathrm{R}_{3} \cdot\left(\frac{\mathrm{~V}_{\mathrm{OUT}(\mathrm{PROTECTION})}}{\mathrm{V}_{\mathrm{OV}}}-1\right)
$$



Figure 9: Over-Voltage Protection Circuit.
If four LEDs are connected in series on one channel, the total $\mathrm{V}_{\mathrm{F}}$ from the WLEDs could be as high as 18.8 V . Therefore, using $\mathrm{R} 3=12.1 \mathrm{k} \Omega$ and setting $\mathrm{V}_{\text {OUT(PROTECTION) }}=20 \mathrm{~V}$ is recommended. Selecting a $1 \%$ resistor, this results in R2 $=187 \mathrm{k} \Omega$ (rounded to the nearest standard $1 \%$ value).

It is always recommended to use the same number of WLEDs on each channel and set the appropriate over-voltage protection. Failure to do so may cause any one of the (5) sink pins to exceed the absolute maximum rating voltage and permanently damage the device in case the channel is disconnected (open circuit failure). Examples of over voltage settings for various strings of series-connected LEDs are shown in Table 3.

## LED Brightness Control

The AAT1236 uses the $I^{2} \mathrm{C}$ interface to program and control LED brightness. The output current of the AAT1236 can be changed successively to brighten or dim the LEDs in smooth transitions (i.e., to fade in or fade out) or in discrete steps, giving the user complete programmability and real-time control of LED brightness.

## Selecting the Schottky Diode

To ensure minimum forward voltage drop and no recovery, high voltage Schottky diodes are recommended for the AAT1236 boost converter. The output diode is selected to maintain acceptable efficiency and reasonable operating junction temperature under full load operating conditions. Forward voltage ( $\mathrm{V}_{\mathrm{F}}$ ) and package thermal resistance ( $\theta_{\mathrm{JA}}$ ) are the dominant factors in selecting a diode. The diode non-repetitive peak forward surge current rating ( $\mathrm{I}_{\text {FSM }}$ ) should be considered for high pulsed load applications, such as camera flash. I IFSM rating drops with increasing conduction period. Manufacturers' datasheets should be reviewed carefully to verify reliability under peak loading conditions. The diode's published current rating may not reflect actual operating conditions and should be used only as a comparative measure between similarly rated devices.

| Number of WLEDs <br> on Each Channel | Total Maximum $\mathbf{V F}_{\mathbf{F}} \mathbf{( V )}$ | $\mathbf{V}_{\text {OUT(PROTECTION) }}(\mathbf{V})$ | $\mathbf{R 3}=\mathbf{1 2 . 1} \mathbf{k} \boldsymbol{\Omega}$ |
| :---: | :---: | :---: | :---: |
|  | $\mathbf{R 2}(\mathbf{k} \boldsymbol{\Omega})$ |  |  |
| 4 | 18.8 | 20 | 187 |
| 3 | 14.1 | 15 | 140 |
| 2 | 9.4 | 10 | 88.7 |

Table 3: Over-Voltage Protection Settings.

20 V rated Schottky diodes are recommended for output voltages less than 15 V , while 30 V rated Schottky diodes are recommended for output voltages higher than 15 V .

## Estimating Schottky Diode Power Dissipation

The switching period is divided between ON and OFF time intervals:

$$
\frac{1}{\mathrm{~F}_{\mathrm{S}}}=\mathrm{T}_{\mathrm{ON}}+\mathrm{T}_{\mathrm{OFF}}
$$

During the ON time, the N-channel power MOSFET is conducting and storing energy in the boost inductor. During the OFF time, the N-channel power MOSFET is not conducting. Stored energy is transferred from the input battery and boost inductor to the output load through the output diode.
Duty cycle is defined as the ON time divided by the total switching interval:

$$
\begin{aligned}
\mathrm{D} & =\frac{\mathrm{T}_{\text {ON }}}{\mathrm{T}_{\text {ON }}+\mathrm{T}_{\text {OFF }}} \\
& =\mathrm{T}_{\text {ON }} \cdot \mathrm{F}_{\mathrm{S}}
\end{aligned}
$$

The maximum duty cycle can be estimated from the relationship for a continuous mode boost converter. Maximum duty cycle ( $\mathrm{D}_{\text {MAX }}$ ) is the duty cycle at minimum input voltage $\left(\mathrm{V}_{\left.\mathbb{I N}_{(M I N}\right)}\right)$ :

$$
D_{\text {MAX }}=\frac{V_{\text {OUT }}-V_{\text {IN(MM) }}}{V_{\text {OUT }}}
$$

The average diode current during the OFF time can be estimated:

$$
I_{\text {AVG(OFF) }}=\frac{I_{\text {OUT }}}{1-D_{\text {MAX }}}
$$

The $V_{F}$ of the Schottky diode can be estimated from the average current during the off time. The average diode current is equal to the output current:

$$
\mathrm{I}_{\mathrm{AVG}(\mathrm{TOT})}=\mathrm{I}_{\mathrm{OUT}}
$$

The average output current multiplied by the forward diode voltage determines the loss of the output diode:

$$
\begin{aligned}
P_{\text {LOSS(IIODE) }} & =I_{\text {AVG(TOT) }} \cdot \mathrm{V}_{\mathrm{F}} \\
& =I_{\text {OUT }} \cdot \mathrm{V}_{\mathrm{F}}
\end{aligned}
$$

For continuous LED currents, the diode junction temperature can then be estimated:

$$
\mathrm{T}_{\mathrm{JDODOE})}=\mathrm{T}_{\mathrm{AMB}}+\theta_{\mathrm{JA}} \cdot \mathrm{P}_{\text {LOSS(DIODE) }}
$$

External Schottky diode junction temperature should be below $110^{\circ} \mathrm{C}$, and may vary depending on application and/or system guidelines. The diode $\theta_{\mathrm{JA}}$ can be minimized with additional metal PCB area on the cathode. However, adding additional heat-sinking metal around the anode may degrade EMI performance. The reverse leakage current of the rectifier must be considered to maintain low quiescent (input) current and high efficiency under light load. The rectifier reverse current increases dramatically at elevated temperatures.

| Manufacturer | Part Number | Rated $\mathbf{I}_{\mathbf{F}(\mathbf{A V})}$ <br> Current $^{(\mathbf{A})^{1}}$ | Rated <br> Voltage (V) | Thermal <br> Resistance <br> $\left(\theta_{\mathrm{JA}},{ }^{\circ} \mathbf{C} / \mathbf{W}\right)^{1}$ | Case |
| :--- | :--- | :---: | :---: | :---: | :---: |
| Diodes, Inc. | B0520WS | 0.50 | 20 | 426 | SOD-323 |
| ON Semi | MBR130LSFT | 1.00 | 30 | 325 | SOD-123 |
| ON Semi | MBR0530T | 0.50 | 30 | 206 | SOD-123 |

Table 4: Typical Surface Mount Schottky Rectifiers for Various Output Loads (select $\mathrm{T}_{\mathrm{J}}<110^{\circ} \mathrm{C}$ in application circuit).

## AAT1236 <br> High Efficiency White LED Drivers for Backlight and Keypad

## Selecting the Boost Inductor

The AAT1236 controllers utilize hysteretic control and the switching frequency varies with output load and input voltage. The value of the inductor determines the maximum switching frequency of the boost converter. Increased output inductance decreases the switching frequency, resulting in higher peak currents and increased output voltage ripple. To maintain 2 MHz maximum switching frequency and stable operation, an output inductor selected between $1.5 \mu \mathrm{H}$ and $2.7 \mu \mathrm{H}$ is recommended.

A better estimate of $D_{\text {MAX }}$ is possible once $V_{F}$ is known:

$$
D_{\text {MAX }}=\frac{\left(V_{\text {OUT }}+V_{F}-V_{\text {INMMN }}\right)}{\left(V_{\text {OUT }}+V_{F}\right)}
$$

Where $\mathrm{V}_{\mathrm{F}}$ is the Schottky diode forward voltage. If not known or not provided by the manufacturer, a starting value of 0.5 V can be used.

Manufacturer's specifications list both the inductor DC current rating, which is a thermal limitation, and peak inductor current rating, which is determined by the saturation characteristics. Measurements at full load and high ambient temperature should be performed to ensure that the inductor does not saturate or exhibit excessive temperature rise.

The output inductor ( L ) is selected to avoid saturation at minimum input voltage and maximum output load conditions. Peak current may be estimated using the following equation, assuming continuous conduction mode. Worst-case peak current occurs at minimum input voltage (maximum duty cycle) and maximum load. Switching frequency $\left(F_{S}\right)$ can be estimated at 500 kHz with a $2.2 \mu \mathrm{H}$ inductor:

$$
\mathrm{I}_{\text {PEAK }}=\frac{\mathrm{I}_{\mathrm{OUT}}}{\left(1-\mathrm{D}_{\mathrm{MAX}}\right)}+\frac{\mathrm{D}_{\mathrm{MAX}} \cdot \mathrm{~V}_{\text {IN(MIN })}}{\left(2 \cdot \mathrm{~F}_{\mathrm{S}} \cdot \mathrm{~L}\right)}
$$

At light load and low output voltage, the controller reduces the operating frequency to maintain maximum operating efficiency. As a result, further reduction in output load does not reduce the peak current. Minimum peak current can be estimated between 0.5 A and 0.75 A .

At high load and high output voltages, the switching frequency is somewhat diminished, resulting in higher $\mathrm{I}_{\text {PEAK }}$. Bench measurements are recommended to confirm actual $I_{\text {PEAK }}$ and to ensure that
the inductor does not saturate at maximum LED current and minimum input supply voltage.

The RMS current flowing through the boost inductor is equal to the DC plus AC ripple components. Under worst-case RMS conditions, the current waveform is critically continuous. The resulting RMS calculation yields worst-case inductor loss. The RMS current value should be compared against the inductor manufacturer's temperature rise, or thermal derating, guidelines:

$$
I_{\mathrm{RMS}}=\frac{\mathrm{I}_{\mathrm{PEAK}}}{\sqrt{3}}
$$

For a given inductor type, smaller inductor size leads to an increase in DCR winding resistance and, in most cases, increased thermal impedance. Winding resistance degrades boost converter efficiency and increases the inductor's operating temperature:

$$
P_{\text {LOSS(INDUCTOR) }}=I_{\text {RMS }}{ }^{2} \cdot \mathrm{DCR}
$$

To ensure high reliability, the inductor case temperature should not exceed $100^{\circ} \mathrm{C}$. In some cases, PCB heatsinking applied to the LIN node (non-switching) can improve the inductor's thermal capability. However, as in the case of adding extra metal around the Schottky's anode, adding extra PCB metal around the AAT1236's SW pin for heatsinking may degrade EMI performance.

Shielded inductors provide decreased EMI and may be required in noise sensitive applications. Unshielded chip inductors provide significant space savings at a reduced cost compared to shielded (wound and gapped) inductors. In general, chiptype inductors have increased winding resistance (DCR) when compared to shielded, wound varieties.

## Selecting the Boost Capacitors

The high output ripple inherent in the boost converter necessitates the use of low impedance output filtering.
Multi-layer ceramic (MLC) capacitors provide small size and adequate capacitance, low parasitic equivalent series resistance (ESR) and equivalent series inductance (ESL), and are well suited for use with the AAT1236 boost regulator. MLC capacitors of type X7R or X5R are recommended to ensure good capacitance stability over the full operating temperature range.

| Manufacturer | Part Number | Inductance <br> $(\boldsymbol{\mu H})$ | Max DC I <br> Current $(\mathbf{A})$ | DCR <br> $(\boldsymbol{\Omega})$ | Size (mm) <br> $\mathbf{L x W} \mathbf{W H}$ | Type |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| Sumida | CDRH4D22/HP-2R2 | 2.2 | 2.50 | 35 | $5.0 \times 5.0 \times 2.4$ | Shielded |
| Sumida | CDR4D11/HP-2R4 | 2.4 | 1.70 | 105 | $4.8 \times 4.8 \times 1.2$ | Shielded |
| Sumida | CDRH4D18-2R2 | 2.2 | 1.32 | 75 | $5.0 \times 5.0 \times 2.0$ | Shielded |
| Murata | LQH662N2R2M03 | 2.2 | 3.30 | 19 | $6.3 \times 6.3 \times 4.7$ | Shielded |
| Murata | LQH55DN2R2M03 | 2.2 | 3.20 | 29 | $5.0 \times 5.7 \times 4.7$ | Non-Shielded |
| Taiyo Yuden | NR4018T2R2 | 2.2 | 2.70 | 60 | $4.0 \times 4.0 \times 1.8$ | Shielded |
| Taiyo Yuden | NR3015T2R2 | 2.2 | 1.48 | 60 | $3.0 \times 3.0 \times 1.5$ | Shielded |
| Coiltronics | SD3814-2R2 | 2.2 | 1.90 | 77 | $3.8 \times 3.8 \times 1.4$ | Shielded |
| Coiltronics | SD3114-2R2 | 2.2 | 1.48 | 86 | $3.1 \times 3.1 \times 1.4$ | Shielded |
| Coiltronics | SD3112-2R2 | 2.2 | 1.12 | 140 | $3.1 \times 3.1 \times 1.2$ | Shielded |

Table 5: Typical Surface Mount Inductors for Various Output Loads (select $I_{\text {PEAK }}<I_{\text {SAT }}$ ).

| Manufacturer | Part Number | Value $(\boldsymbol{\mu F})$ | Voltage Rating | Temp Co | Case Size |
| :--- | :---: | :---: | :---: | :---: | :---: |
| Murata | GRM188R60J225KE19 | 2.2 | 6.3 | X5R | 0603 |
| Murata | GRM21BR71A225KA01 | 2.2 | 10 | X7R | 0805 |
| Murata | GRM219R61E225KA12 | 2.2 | 25 | X5R | 0805 |
| Murata | GRM21BR71E225KA73L | 2.2 | 25 | X7R | 0805 |
| Murata | GRM21BR61E475KA12 | 4.7 | 25 | X5R | 0805 |

Table 6: Recommended Ceramic Capacitors.

The output capacitor is selected to maintain the output load without significant voltage droop ( $\Delta \mathrm{V}_{\text {OUT }}$ ) during the power switch ON interval, when the output diode is not conducting. A ceramic output capacitor from $2.2 \mu \mathrm{~F}$ to $4.7 \mu \mathrm{~F}$ is recommended (see Table 6).

Typically, 25 V rated capacitors are required for the 24 V maximum boost output. Ceramic capacitors selected as small as 0805 are available which meet these requirements.

MLC capacitors exhibit significant capacitance reduction with applied voltage. Output ripple measurements should confirm that output voltage droop and operating stability are within acceptable limits. Voltage derating can minimize this factor, but results may vary with package size and among specific manufacturers.

Output capacitor size can be estimated at a switching frequency ( $\mathrm{F}_{\mathrm{S}}$ ) of 500 kHz (worst case):

$$
C_{\text {OUT }}=\frac{I_{\text {OUT }} \cdot D_{\text {MAX }}}{F_{S} \cdot \Delta V_{\text {OUT }}}
$$

To maintain stable operation at full load, the output capacitor should be selected to maintain $\Delta \mathrm{V}_{\text {OUT }}$ between 100 mV and 200 mV .

The boost converter input current flows during both ON and OFF switching intervals. The input ripple current is less than the output ripple and, as a result, less input capacitance is required.

## PCB Layout Guidelines

Boost converter performance can be adversely affected by poor layout. Possible impact includes high input and output voltage ripple, poor EMI performance, and reduced operating efficiency. Every attempt should be made to optimize the layout in order to minimize parasitic PCB effects (stray resistance, capacitance, and inductance) and EMI coupling from the high frequency SW node. A suggested PCB layout for the AAT1236 boost converter is shown in Figures 10 and 11. The following PCB layout guidelines should be considered:

1. Minimize the distance from Capacitor C 1 and C2's negative terminals to the GND pins. This is especially true with output capacitor C2, which conducts high ripple current from the output diode back to the GND pins.


Figure 10: AAT1236 Evaluation Board Top Side Layout.
2. Minimize the distance between L1 to D1 and switching pin SW; minimize the size of the PCB area connected to the SW pin.
3. Maintain a ground plane and connect to the IC GND pin(s) as well as the GND connections of C1 and C2.
4. Consider additional PCB metal area on D1's cathode to maximize heatsinking capability. This may be necessary when using a diode with a high $\mathrm{V}_{\mathrm{F}}$ and/or thermal resistance.
5. Do not connect the exposed paddle (bottom of the die) to either AGND or GND because it is connected internally to SW. Connect the exposed paddle to the SW pin or leave floating.


Figure 11: AAT1236 Evaluation Board Bottom Side Layout.


Figure 12: Exploded View of AAT1236 Evaluation Board Top Side Layout Detailing Plated Through Vias.

## Ordering Information

| Package | Marking $^{1}$ | Part Number (Tape and Reel) ${ }^{1}$ |
| :---: | :---: | :---: |
| TDFN34-16 | UDXYY | AAT1236IRN-T1 |

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## Package Information ${ }^{3}$



TDFN34-16

Detail "A"
All dimensions in millimeters.

1. $X Y Y=$ assembly and date code.
2. Sample stock is generally held on part numbers listed in BOLD.
3. The leadless package family, which includes QFN, TQFN, DFN, TDFN and STDFN, has exposed copper (unplated) at the end of the lead terminals due to the manufacturing process. A solder fillet at the exposed copper edge cannot be guaranteed and is not required to ensure a proper bottom solder connection.

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[^0]:    1. Stresses above those listed in Absolute Maximum Ratings may cause permanent damage to the device. Functional operation at conditions other than the operating conditions specified is not implied. Only one Absolute Maximum Rating should be applied at any one time.
    2. Mounted on an FR4 circuit board.
    3. Derate $20 \mathrm{~mW}^{\circ} \mathrm{C}$ above $40^{\circ} \mathrm{C}$ ambient temperature.
